

LM95071 SPI/MICROWIRE 13-Bit Plus Sign Temperature Sensor

1 Features

- Small SOT-23 package saves space
- Shutdown mode conserves power between temperature readings
- Operates over a full -40°C to $+150^{\circ}\text{C}$ range
- SPI and MICROWIRE bus interface
- Key specifications:
 - Supply voltage: 2.4 V to 5.5 V
 - Supply current:
 - Operating: 280 μA (typical)
 - Shutdown: 6 μA (typical)
 - Temperature accuracy:
 - 0°C to $70^{\circ}\text{C} \pm 1^{\circ}\text{C}$ (maximum)
 - -40°C to $150^{\circ}\text{C} \pm 2^{\circ}\text{C}$ (maximum)
 - Temperature resolution: 0.03125 $^{\circ}\text{C}$

2 Applications

- System thermal management
- Portable electronic devices
- Personal computers
- Disk drives
- Office electronics
- Electronic test equipment

3 Description

The LM95071 is a low-power, high-resolution digital temperature sensor with an SPI and MICROWIRE compatible interface, available in the 5-pin SOT-23. The host can query the LM95071 at any time to read temperature. Its low operating current is useful in systems where low power consumption is critical.

The LM95071 has 13-bit plus sign temperature resolution (0.03125 $^{\circ}\text{C}$ per LSB) while operating over a temperature range of -40°C to $+150^{\circ}\text{C}$.

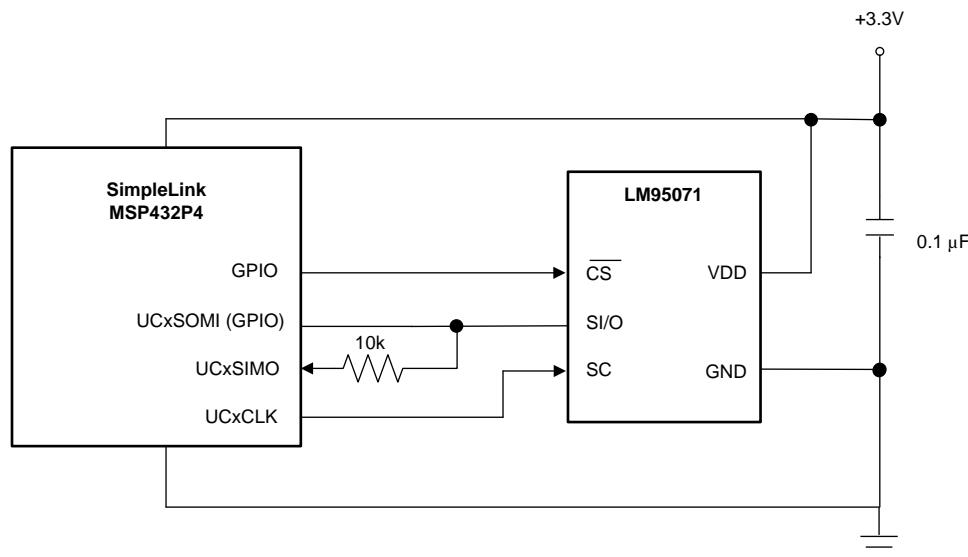
The 2.4-V to 5.5-V supply voltage range, fast conversion rate, low supply current, and simple SPI interface of the LM95071 make it ideal for a wide range of applications.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM95071	SOT-23 (5)	2.90 mm x 1.60 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Temperature Monitor Application



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

Table of Contents

1	Features	1	7	Parameter Measurement Information	8
2	Applications	1	8	Detailed Description	9
3	Description	1	8.1	Overview	9
4	Revision History	2	8.2	Functional Block Diagram	9
5	Pin Configuration and Functions	3	8.3	Feature Description	9
6	Specifications	3	8.4	Device Functional Modes	10
6.1	Absolute Maximum Ratings	3	8.5	Programming	10
6.2	ESD Ratings	3	8.6	Register Maps	12
6.3	Recommended Operating Ratings	4	9	Device and Documentation Support	14
6.4	Thermal Information	4	9.1	Receiving Notification of Documentation Updates ..	14
6.5	Temperature-to-Digital Converter Characteristics	4	9.2	Community Resource	14
6.6	Logic Electrical Characteristics - Digital DC Characteristics	4	9.3	Trademarks	14
6.7	Logic Electrical Characteristics - Serial Bus Digital Switching Characteristics	5	9.4	Electrostatic Discharge Caution	14
6.8	Timing Diagrams	5	9.5	Glossary	14
6.9	Typical Characteristics	7	10	Mechanical, Packaging, and Orderable Information	14

4 Revision History

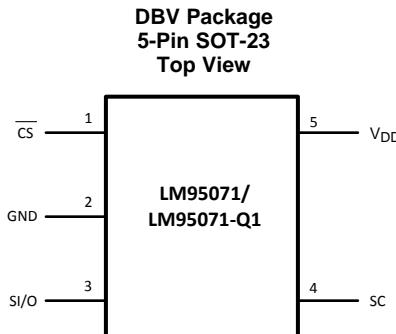
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (May 2019) to Revision G	Page
• Changed <i>Temperature Monitor Application</i> graphic	1

Changes from Revision E (December 2018) to Revision F	Page
• Added the TYPE column to the <i>Pin Functions</i> table	3
• Changed $V_{(ESD)}$ for CDM from ± 200 V to ± 250 V	3

Changes from Revision D (September 2013) to Revision E	Page
• Updated data sheet layout to the latest SDS format	1
• Moved the automotive device to a standalone data sheet (SNIS207)	1
• Added <i>Device Information</i> table, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Changed key graphics on the first page	1
• Replaced the <i>Thermal Characteristics</i> table with the <i>Thermal Information</i> table and added new thermal resistance values	4
• Changed Temperature-to-Digital Converter Characteristics tablenote to clarify conversion interval	4

5 Pin Configuration and Functions



Pin Function

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	CS	Input	Chip Select input. This pin receives an active-low signal from the controller to select the device.
2	GND	Ground	Ground. This is the power and signal ground return.
3	SI/O	Input/Output	Serial Input/Output. This serial, bidirectional, data bus pin transmits and receives signals to and from the controller. Schmitt trigger input in the input mode.
4	SC	Input	Serial bus clock. This serial clock signal comes from the controller. Schmitt trigger input.
5	V _{DD}	Supply	Positive Supply Voltage. Supply a DC voltage from 2.4V to 5.5V to this pin and bypass with a 0.1- μ F ceramic capacitor to ground.

6 Specifications

6.1 Absolute Maximum Ratings ⁽¹⁾⁽²⁾⁽³⁾

	MIN	MAX	UNIT
Supply voltage	-0.3	6	V
Voltage at any pin	-0.3	V _{DD} + 0.3	V
Input current at any pin ⁽⁴⁾	5		mA
Storage temperature, T _{stg}	-65	150	°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its rated operating conditions.
- (2) Soldering process must comply with Reflow Temperature Profile specifications. Refer to <http://www.ti.com/packaging>.
- (3) Reflow temperature profiles are different for lead-free and non-lead-free packages.
- (4) When the input voltage (V_I) at any pin exceeds the power supplies (V_I < GND or V_I > V_{DD}) the current at that pin should be limited to 5 mA.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾⁽²⁾	±2000 ±250
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽³⁾	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) Human body model, 100 pF discharged through a 1.5 k Ω resistor. Machine model, 200 pF discharged directly into each pin.
- (3) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Ratings

	MIN	MAX	UNIT
Specified temperature ⁽¹⁾ , T_{MIN} to T_{MAX}	-40	150	°C
Supply voltage (V_{DD})	2.4	5.5	V

(1) The life expectancy of the LM95071 will be reduced when operating at elevated temperatures. of the LM95071 θ_{JA} (thermal resistance, junction-to-ambient) when attached to a printed-circuit board with 2-oz. foil is summarized in the table below.

6.4 Thermal Information

THERMAL METRIC⁽¹⁾		LM95071	UNIT
		DBV (SOT-23)	
		5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	167.2	°C/W
$R_{\theta JC(\text{top})}$	Junction-to-case (top) thermal resistance	118.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	30.7	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	14.4	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	30.1	°C/W
$R_{\theta JC(\text{bot})}$	Junction-to-case (bottom) thermal resistance	n/a	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Temperature-to-Digital Converter Characteristics

Unless otherwise noted, these specifications apply for $V_{DD} = 3.3$ V. All limits $T_A = T_J = +25$ °C, unless otherwise noted.

PARAMETER	TEST CONDITIONS		MIN⁽¹⁾	TYP⁽²⁾	MAX⁽¹⁾	UNIT
Temperature error ⁽³⁾	$V_{DD} = 3.0$ V to 3.6 V; $T_A = 0$ °C to $+70$ °C, $T_A = T_J = T_{MIN}$ to T_{MAX}				± 1.0	°C
	$V_{DD} = 3.0$ V to 3.6 V; $T_A = -40$ °C to $+150$ °C, $T_A = T_J = T_{MIN}$ to T_{MAX}				± 2.0	°C
Line regulation	$V_{DD} = 3.6$ V to 5.5 V; $T_A = 0$ °C to $+70$ °C				$+0.3$	°C/V
	$V_{DD} = 3.0$ V to 2.4 V; $T_A = 0$ °C to $+70$ °C				-0.6	
Resolution			14	0.03125		Bits °C
Temperature conversion time	See ⁽⁴⁾	$T_A = T_J = +25$ °C		130		ms
		$T_A = T_J = T_{MIN}$ to T_{MAX}			228	
Quiescent current	Operating, serial bus inactive	$T_A = T_J = +25$ °C		280		μA
		$T_A = T_J = T_{MIN}$ to T_{MAX}			520	
	Shutdown	$T_A = T_J = +25$ °C		6		μA
		$T_A = T_J = T_{MIN}$ to T_{MAX}			28	

(1) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).
(2) Typicals are at $T_A = 25$ °C and represent most likely parametric norm.
(3) The of the LM95071 will operate properly over the V_{DD} supply voltage range of 2.4V to 5.5V.
(4) Following a power on reset, the user must allow at least 228 ms before making the first read transaction to ensure a first valid temperature read. After the first read, in order to ensure an accurate temperature result, the time interval between any two consecutive temperature reads must be greater than the maximum conversion time of 228 ms.

6.6 Logic Electrical Characteristics - Digital DC Characteristics

Unless otherwise noted, these specifications apply for $V_{DD} = 2.4$ V to 5.5 V⁽¹⁾.

PARAMETER	TEST CONDITIONS		MIN⁽²⁾	TYP⁽³⁾	MAX⁽²⁾	UNIT
$V_{IN(1)}$	Logical "1" Input Voltage	$T_A = T_J = T_{MIN}$ to T_{MAX}	$0.7 \times V_{DD}$		$V_{DD} + 0.3$	V
$V_{IN(0)}$	Logical "0" Input Voltage	$T_A = T_J = T_{MIN}$ to T_{MAX}	-0.3		$0.3 \times V_{DD}$	V

(1) The of the LM95071 will operate properly over the V_{DD} supply voltage range of 2.4V to 5.5V.

(2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

(3) Typicals are at $T_A = 25$ °C and represent most likely parametric norm.

Logic Electrical Characteristics - Digital DC Characteristics (continued)

Unless otherwise noted, these specifications apply for $V_{DD} = 2.4\text{ V to }5.5\text{ V}^{(1)}$.

PARAMETER	TEST CONDITIONS	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
Input Hysteresis Voltage	$V_{DD} = 3\text{ V to }3.6\text{ V}$	$T_A = T_J = +25^\circ\text{C}$	0.4		V
$I_{IN(1)}$	$V_{IN} = V_{DD}$	$T_A = T_J = +25^\circ\text{C}$	0.005		
		$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$		3	μA
$I_{IN(0)}$	$V_{IN} = 0\text{ V}$	$T_A = T_J = +25^\circ\text{C}$	-0.005		
		$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-3		μA
C_{IN}	All Digital Inputs	$T_A = T_J = +25^\circ\text{C}$		20	pF
V_{OH}	High Level Output Voltage	$I_{OH} = -400\text{ }\mu\text{A}, T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	2.25		V
V_{OL}	Low Level Output Voltage	$I_{OL} = +1.6\text{ mA}, T_A = T_J = T_{MIN} \text{ to } T_{MAX}$		0.4	V
$I_{O_TRI-STATE}$	$V_O = \text{GND}$ $V_O = V_{DD}, T_A = T_J = T_{MIN} \text{ to } T_{MAX}$		-1	+1	μA

6.7 Logic Electrical Characteristics - Serial Bus Digital Switching Characteristics

Unless otherwise noted, these specifications apply for $V_{DD} = 2.4\text{ V to }5.5\text{ V}^{(1)}$; C_L (load capacitance) on output lines = 100 pF unless otherwise specified.

		MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
t_1	SC (Clock) Period	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$		0.16	
		$T_A = T_J = +25^\circ\text{C}$		DC	μs
t_2	\overline{CS} Low to SC (Clock) High Set-Up Time	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	100		ns
t_3	\overline{CS} Low to Data Out (SO) Delay	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$		70	ns
t_4	SC (Clock) Low to Data Out (SO) Delay	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$		70	ns
t_5	\overline{CS} High to Data Out (SO) TRI-STATE	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$		200	ns
t_6	SC (Clock) High to Data In (SI) Hold Time	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	50		ns
t_7	Data In (SI) Set-Up Time to SC (Clock) High	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	30		ns
t_8	SC (Clock) High to \overline{CS} High Hold Time	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	50		ns

(1) The of the LM95071 will operate properly over the V_{DD} supply voltage range of 2.4V to 5.5V.

(2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

(3) Typicals are at $T_A = 25^\circ\text{C}$ and represent most likely parametric norm.

6.8 Timing Diagrams

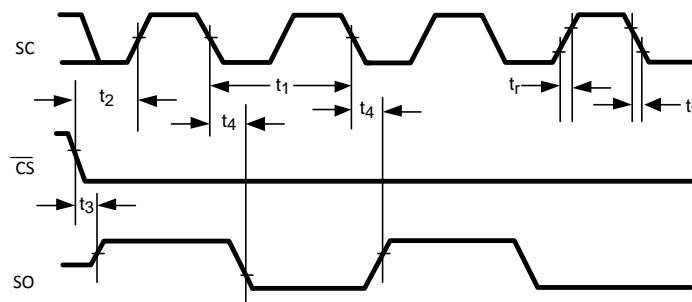


Figure 1. Data Output Timing Diagram

Timing Diagrams (continued)

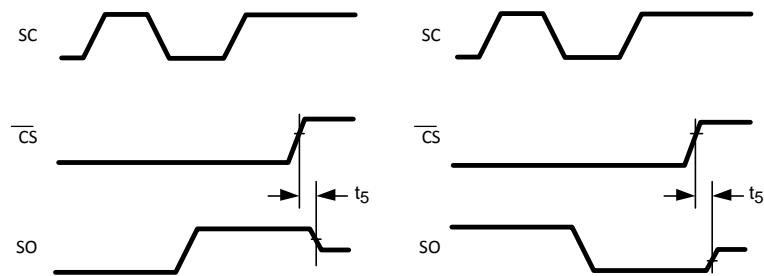


Figure 2. TRI-STATE Data Output Timing Diagram

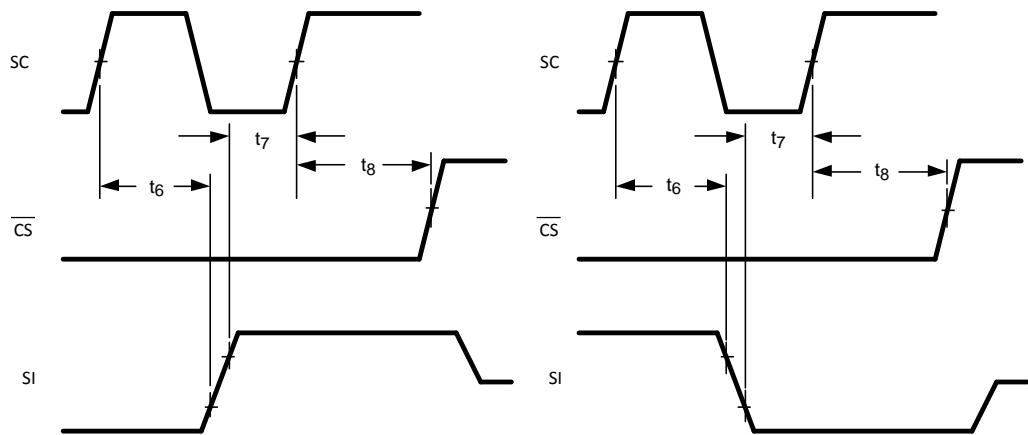


Figure 3. Data Input Timing Diagram

6.9 Typical Characteristics

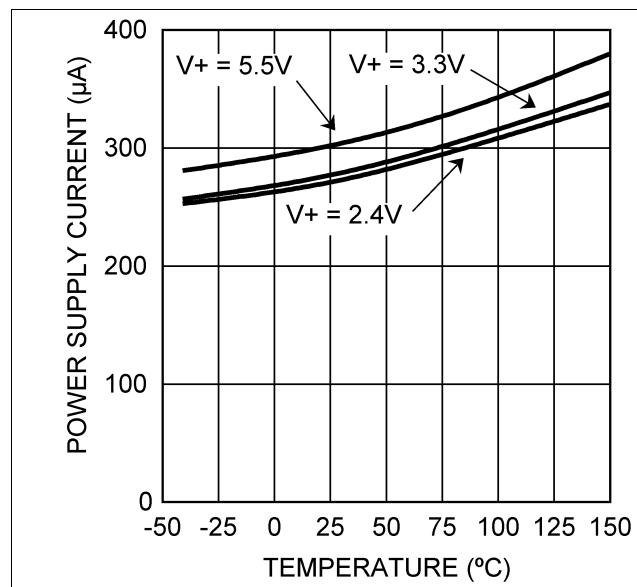


Figure 4. Static Supply Current vs. Temperature

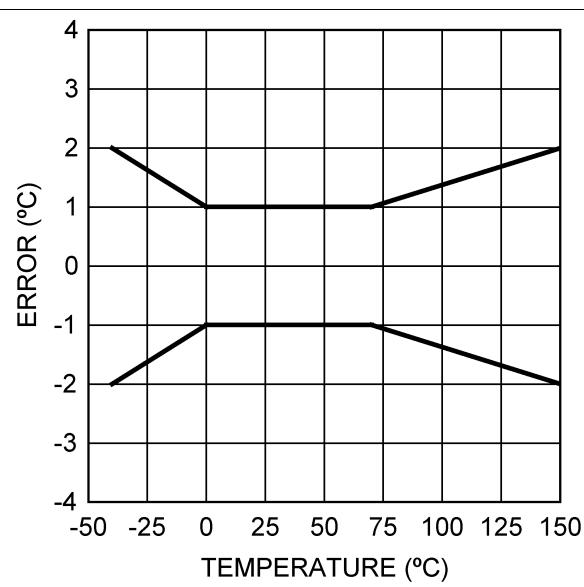


Figure 5. Maximum Temperature Error

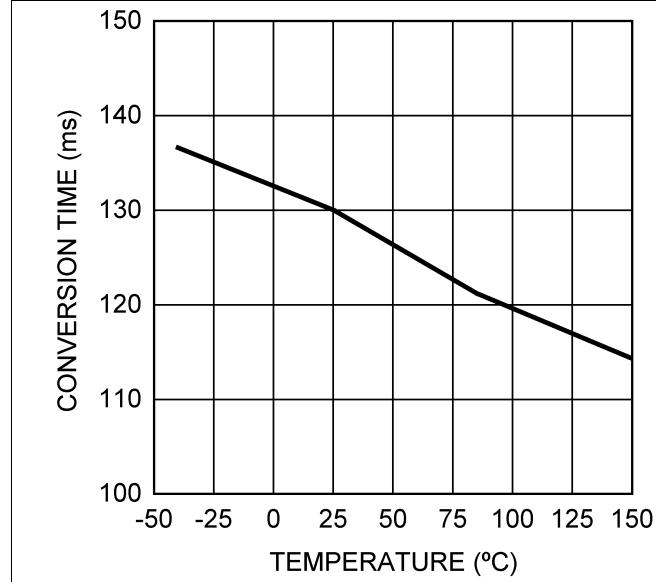


Figure 6. Conversion Time vs Temperature

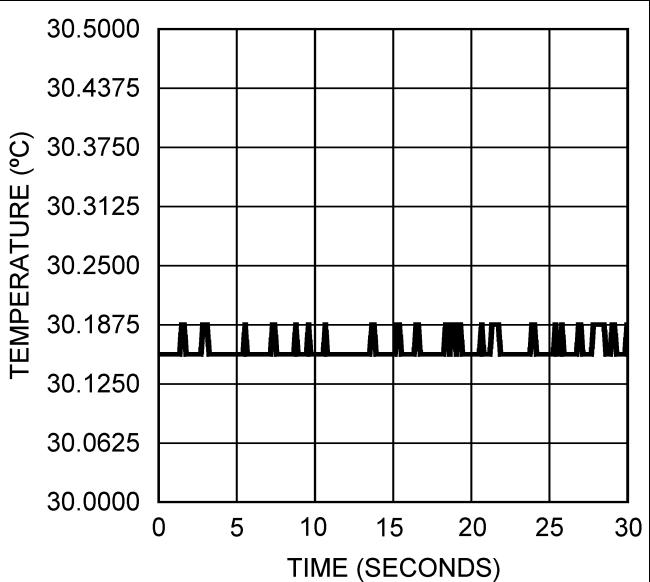


Figure 7. Typical Output Noise at 30°C

7 Parameter Measurement Information

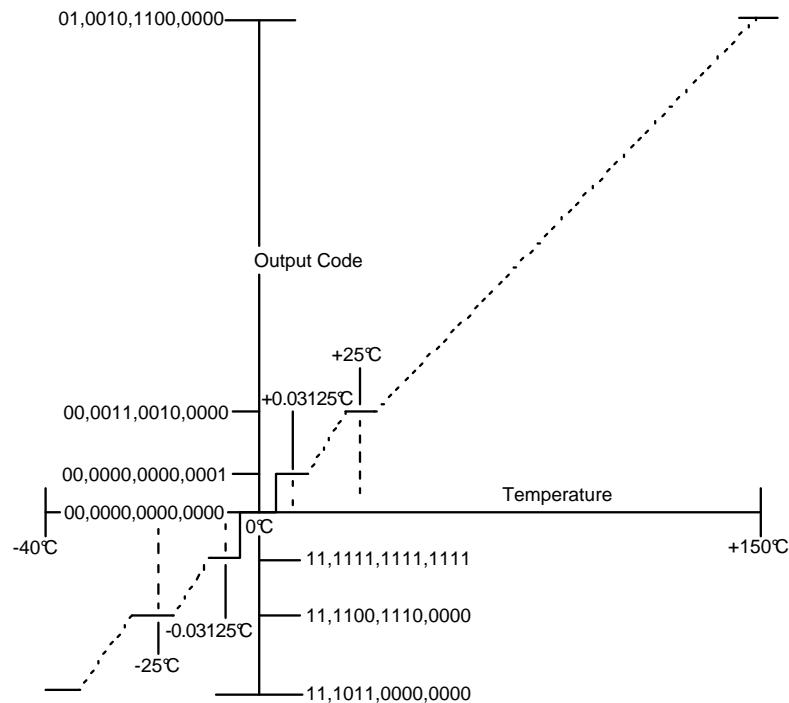


Figure 8. Temperature-to-Digital Transfer Function (Non-Linear Scale for Clarity)

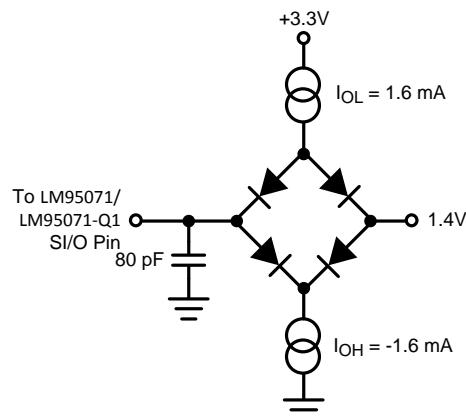


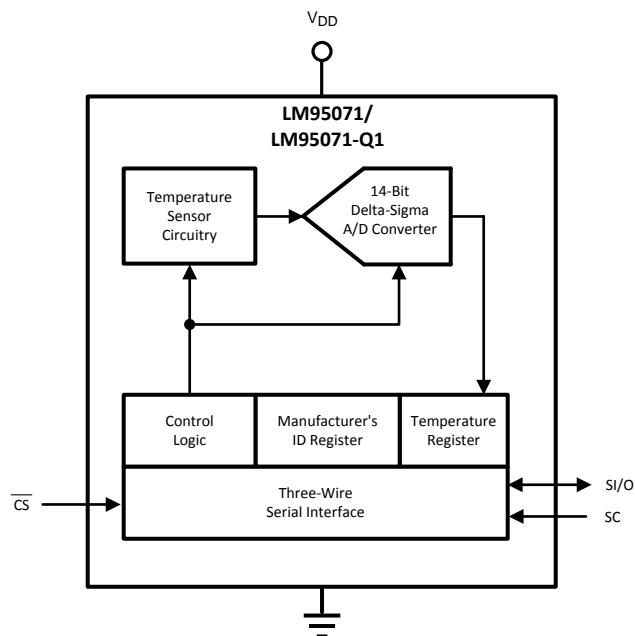
Figure 9. TRI-STATE Test Circuit

8 Detailed Description

8.1 Overview

The LM95071 temperature sensor incorporates a temperature sensor and 13-bit-plus-sign $\Delta\Sigma$ ADC (Delta-Sigma Analog-to-Digital Converter). Compatibility of the LM95071's three-wire serial interface with SPI and MICROWIRE allows simple communications with common microcontrollers and processors. Shutdown mode can be used to optimize current drain for different applications. A Manufacturer/Device ID register identifies the LM95071 as a Texas Instruments product.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Power Up and Power Down

The LM95071 always powers up in a known state and in the continuous conversion mode. Immediately after power up, the LM95071 will output an erroneous code until the first temperature conversion has completed.

When the supply voltage is less than about 1.6V (typical), the LM95071 is considered powered down. As the supply voltage rises above the nominal 1.6-V power up threshold, the internal registers are reset to the power up default state described above.

8.3.2 Temperature Data Format

Temperature data is represented by a 14-bit, two's complement word with an LSB (Least Significant Bit) equal to 0.03125°C:

Table 1. Digital Output for Temperature Data

Temperature	Digital Output	
	Binary	Hex
+150°C	0100 1011 0000 0011	4B03
+125°C	0011 1110 1000 0011	3E83
+25°C	0000 1100 1000 0011	0C83
+0.03125°C	0000 0000 0000 0111	0007
0°C	0000 0000 0000 0011	0003

Table 1. Digital Output for Temperature Data (continued)

Temperature	Digital Output	
	Binary	Hex
-0.03125°C	1111 1111 1111 1111	FFFF
-25°C	1111 0011 1000 0011	F383
-40°C	1110 1100 0000 0011	EC03

The first data byte is the most significant byte with most significant bit first, permitting only as much data as necessary to be read to determine temperature condition. For instance, if the first four bits of the temperature data indicate an overtemperature condition, the host processor could immediately take action to remedy the excessive temperatures.

8.3.3 Tight Accuracy, Fine Resolution and Low Noise

The LM95071 is well suited for applications that require tight temperature measurement accuracy. In many applications, from process control to HVAC, the low temperature error can mean better system performance and, by eliminating a system calibration step, lower production cost.

With fine digital resolution, the LM95071 senses and reports very small changes in its temperature, making it ideal for applications where temperature sensitivity is important. For example, the LM95071 enables the system to quickly identify the direction of temperature change, allowing the processor to take compensating action before the system reaches a critical temperature.

The LM95071 has very low output noise (see [Figure 7](#) in the *Typical Characteristics* section), which makes it ideal for applications where stable thermal compensation is a priority. For example, in a temperature-compensated oscillator application, the very small deviation in successive temperature readings translates to a stable frequency output from the oscillator.

8.4 Device Functional Modes

8.4.1 Shutdown Mode/Manufacturer ID

The master controller may enable the shutdown mode for the purpose of reducing power consumption or for reading the Manufacturer/Device ID information. The shutdown mode is enabled by writing XX FF hex to the LM95071 as shown in [Figure 13c](#). The serial bus is still active when the LM95071 is in shutdown. When in shutdown mode the LM95071 always will output 1000 0000 0000 1111. This is the Manufacturer/Device ID information. The first 5-bits of the field (1000 0XXX) are reserved for the manufacturer ID.

8.5 Programming

8.5.1 Serial Bus Interface

The LM95071 operates as a slave and is compatible with SPI or MICROWIRE bus specifications. Data is clocked out on the falling edge of the serial clock (SC), while data is clocked in on the rising edge of SC. A complete communication is framed by falling and rising chip select (CS) signal. The CS signal should be held high for at least one clock cycle (160 ns minimum) between communications. The transmit-only communication (register read) consists of 16 clock cycles. A complete transmit/receive communication will consist of 32 serial clocks (see [Serial Bus Timing Diagrams](#)). The first 16 clocks comprise the transmit phase of communication, while the second 16 clocks are the receive phase.

When \overline{CS} is high SI/O will be in TRI-STATE. Communication should be initiated by taking chip select (\overline{CS}) low. This should not be done when SC is changing from a low to high state. Once \overline{CS} is low the serial I/O pin (SI/O) will transmit the first bit of data. The master can then read this bit with the rising edge of SC. The remainder of the data will be clocked out by the falling edge of SC. \overline{CS} can be taken high at any time during the transmit phase. If \overline{CS} is brought low in the middle of a conversion the LM95071 will complete the conversion and the output shift register will be updated after \overline{CS} is brought back high.

Programming (continued)

The receive phase of a communication starts after 16 SC periods. \overline{CS} can remain low for 32 SC cycles. The LM95071/LM95071-Q1 will read the data available on the SI/O line on the rising edge of the serial clock. Input data is to an 8-bit shift register. The part will detect the last eight bits shifted into the register. The receive phase can last up to 16 SC periods. All ones must be shifted in order to place the part into shutdown. All zeros must be shifted in order to place the LM95071 into continuous conversion mode. Only the following codes should be transmitted to the LM95071:

- 00 hex for continuous conversion
- FF hex for shutdown

Another code may place the part into a test mode. Test modes are used by Texas Instruments to thoroughly test the function of the LM95071 during production testing. Only eight bits have been defined above since only the last eight transmitted are detected by the LM95071, before \overline{CS} is taken HIGH.

The following communication can be used to determine the Manufacturer's/Device ID and then immediately place the part into continuous conversion mode. With \overline{CS} continuously low:

- Read 16 bits of temperature data
- Write 16 bits of data commanding shutdown
- Read 16 bits of Manufacturer's/Device ID data
- Write 8 to 16 bits of data commanding Conversion Mode
- Take \overline{CS} HIGH.

Note that 228 ms (max) will have to pass for a conversion to complete before the LM95071 actually transmits temperature data.

8.5.2 Serial Bus Timing Diagrams

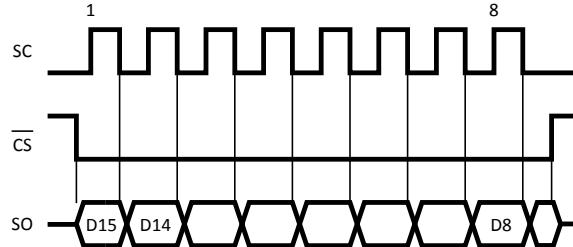


Figure 10. Reading Continuous Conversion - Single Eight-Bit Frame

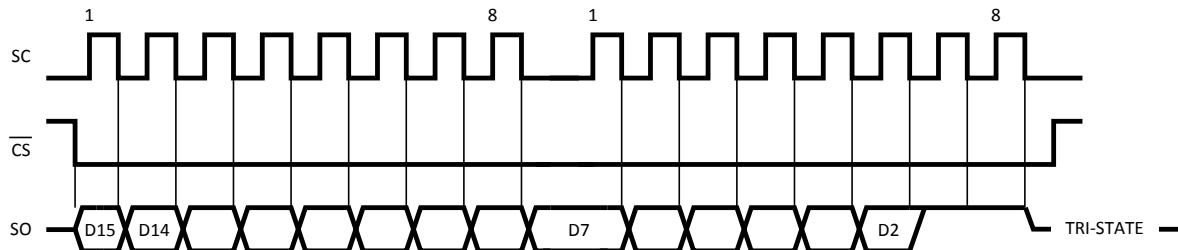


Figure 11. Reading Continuous Conversion - Two Eight-Bit Frames

Programming (continued)

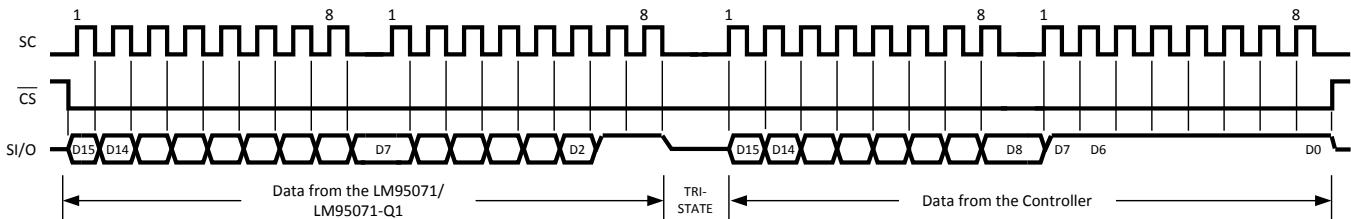


Figure 12. Writing Shutdown Mode

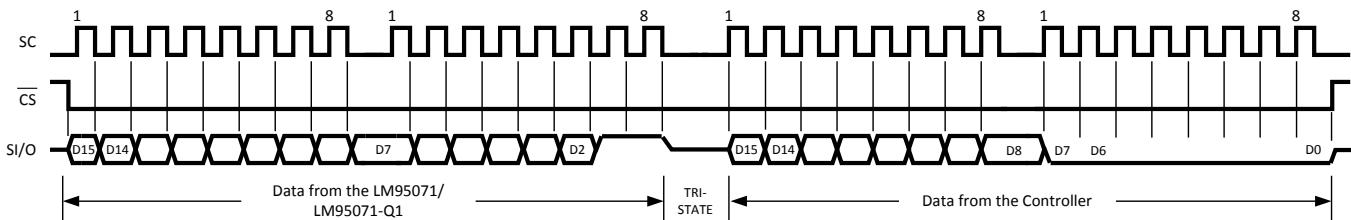


Figure 13. Writing Conversion Mode

8.6 Register Maps

8.6.1 Internal Register Structure

The LM95071 has three registers: the temperature register, the configuration register and the Manufacturer/Device identification register. The temperature and Manufacturer/Device identification registers are read only. The configuration register is write only.

8.6.1.1 Configuration Register

(Selects shutdown or continuous conversion modes):

Table 2. (Write Only):

D0–D15 set to XX FF hex enables shutdown mode.

D0–D15 set to XX 00 hex sets continuous-conversion mode.

Note: setting D0-D15 to any other values may place the LM95071 into a manufacturer's test mode, upon which the LM95071 will stop responding as described. These test modes are to be used for Texas Instruments production testing only. See [Serial Bus Interface](#) for a complete discussion.

8.6.1.2 Temperature Register

Table 3. (Read Only):

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
MSB	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit1	LSB	1	1

D0–D1: Logic 1 will be output on SI/0.

D2–D15: Temperature Data. One LSB = 0.03125°C. Two's complement format.

8.6.1.3 Manufacturer/Device ID Register

Table 4. (Read Only):

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
1	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1

D0–D1: Logic 1 will be output on SI/0.

D2–D15: Manufacturer/Device ID Data. This register is accessed whenever the LM95071 is in shutdown mode.

9 Device and Documentation Support

9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.2 Community Resource

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

9.3 Trademarks

E2E is a trademark of Texas Instruments.

TRI-STATE is a registered trademark of National Semiconductor Corporation.

All other trademarks are the property of their respective owners.

9.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

9.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM95071CIMF	NRND	Production	SOT-23 (DBV) 5	1000 SMALL T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 150	T18C
LM95071CIMF.A	NRND	Production	SOT-23 (DBV) 5	1000 SMALL T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 150	T18C
LM95071CIMF/NOPB	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	-40 to 150	T18C
LM95071CIMFX	NRND	Production	SOT-23 (DBV) 5	3000 LARGE T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 150	T18C
LM95071CIMFX.A	NRND	Production	SOT-23 (DBV) 5	3000 LARGE T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 150	T18C
LM95071CIMFX/NOPB	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 150	T18C
LM95071CIMFX/NOPB.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 150	T18C

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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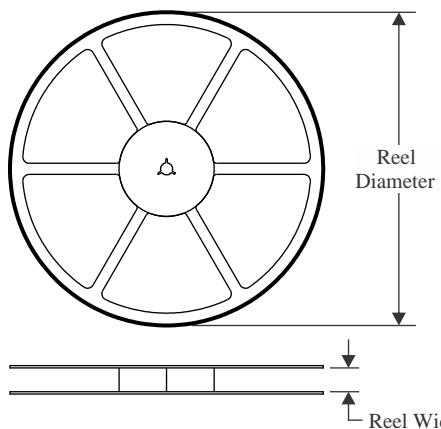
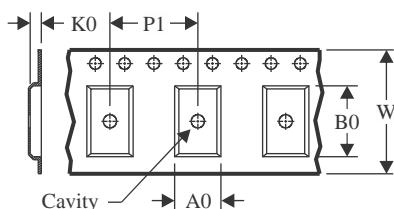
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LM95071 :

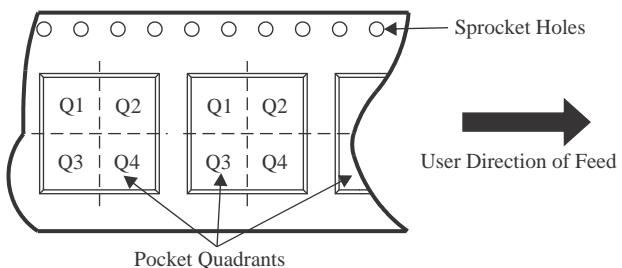
- Automotive : [LM95071-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM95071CIMFX/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM95071CIMFX/NOPB	SOT-23	DBV	5	3000	208.0	191.0	35.0

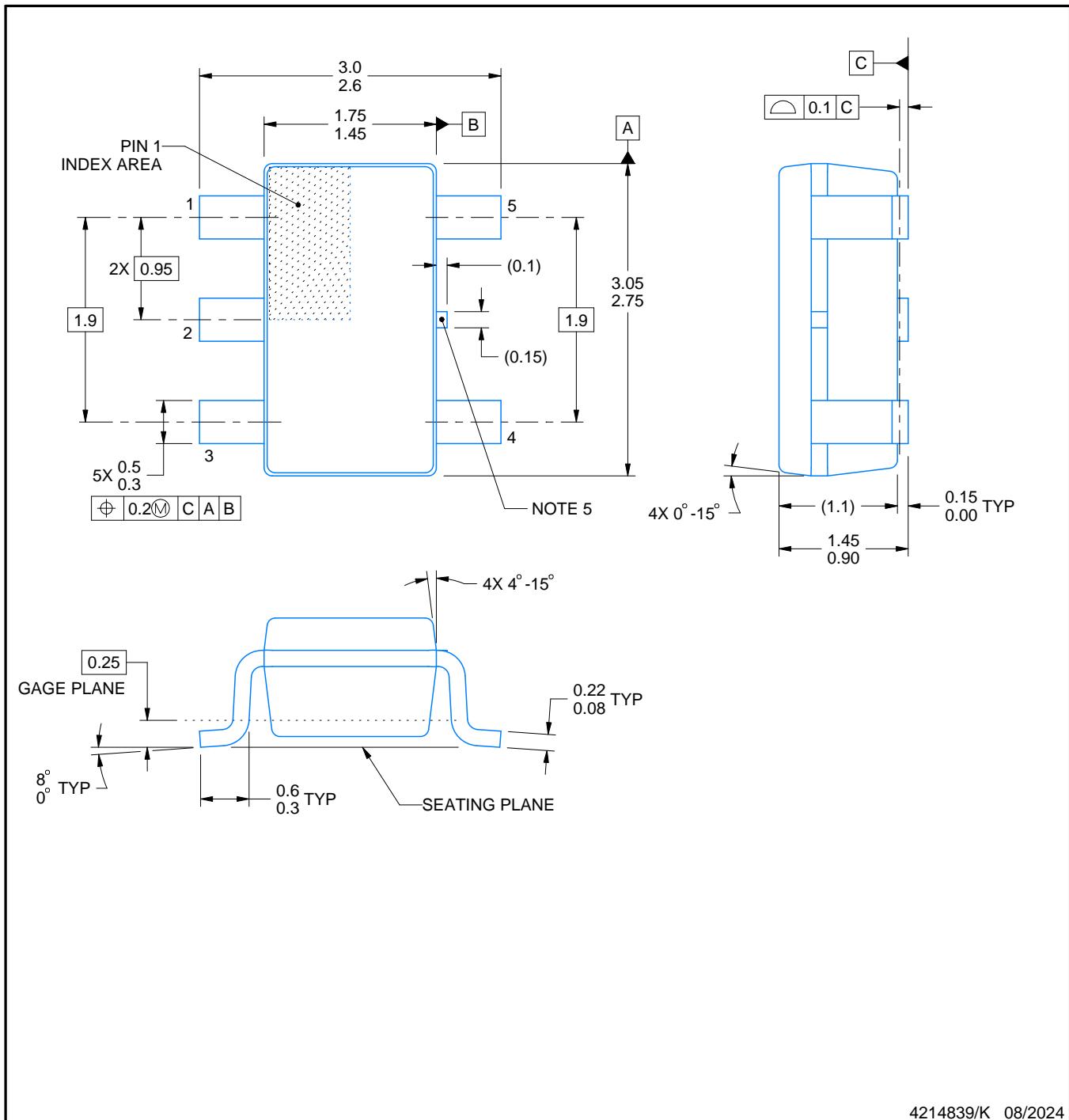
PACKAGE OUTLINE

DBV0005A



SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



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NOTES:

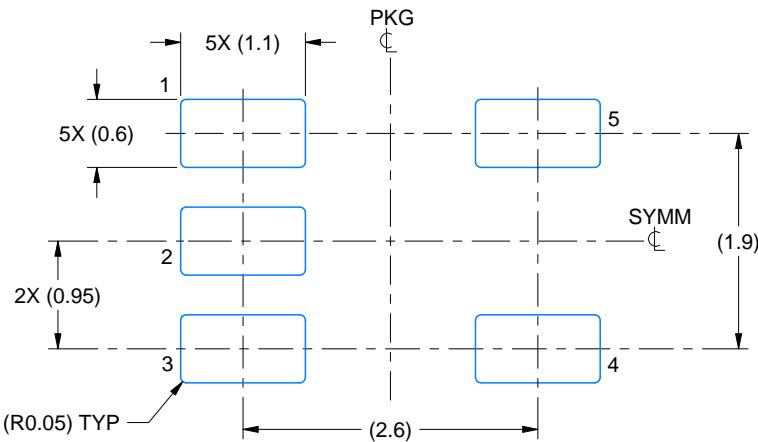
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

EXAMPLE BOARD LAYOUT

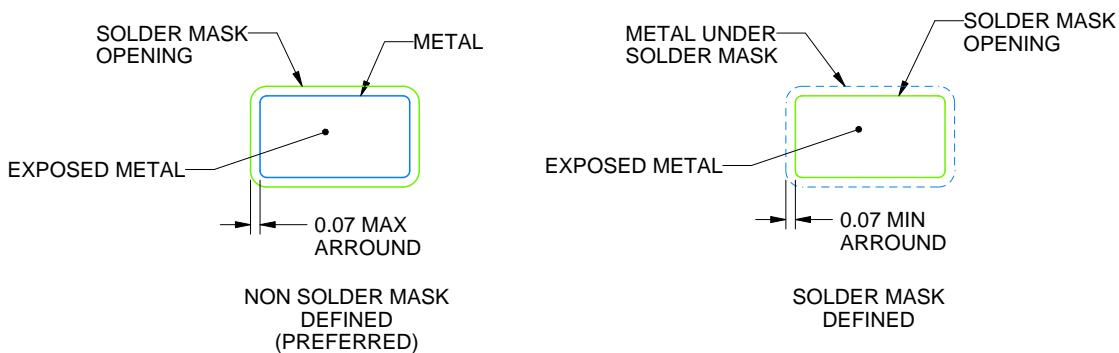
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

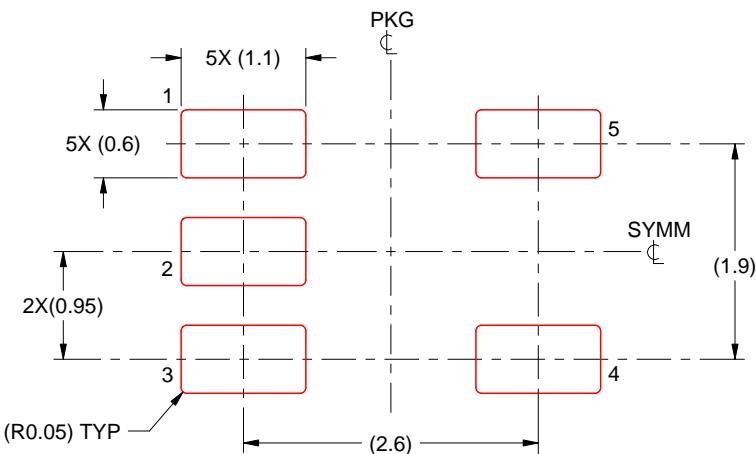
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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